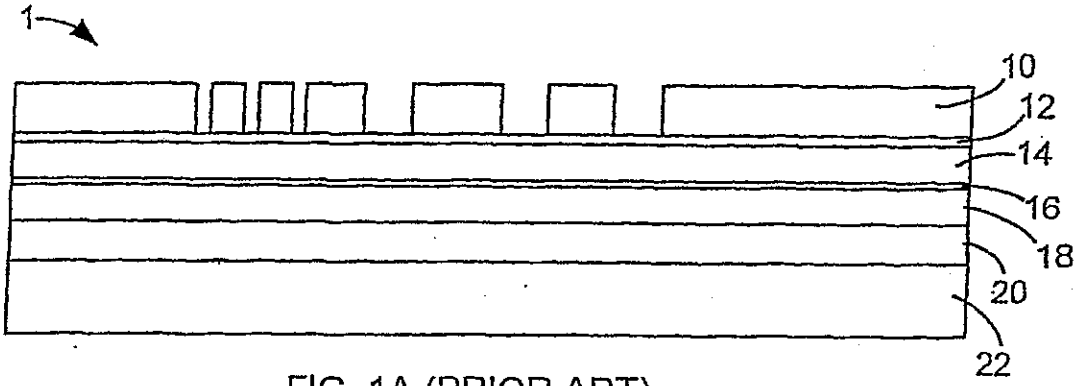


FIG. 1A (PRIOR ART)

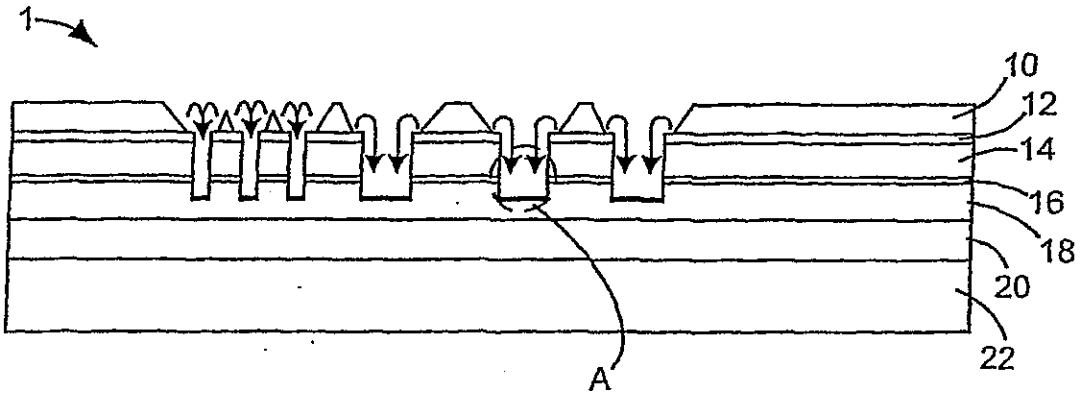


FIG. 1B (PRIOR ART)

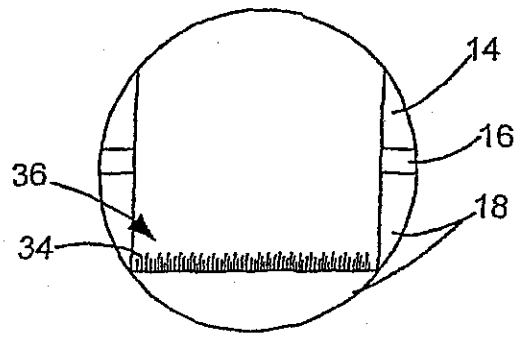


FIG. 1C (PRIOR ART)

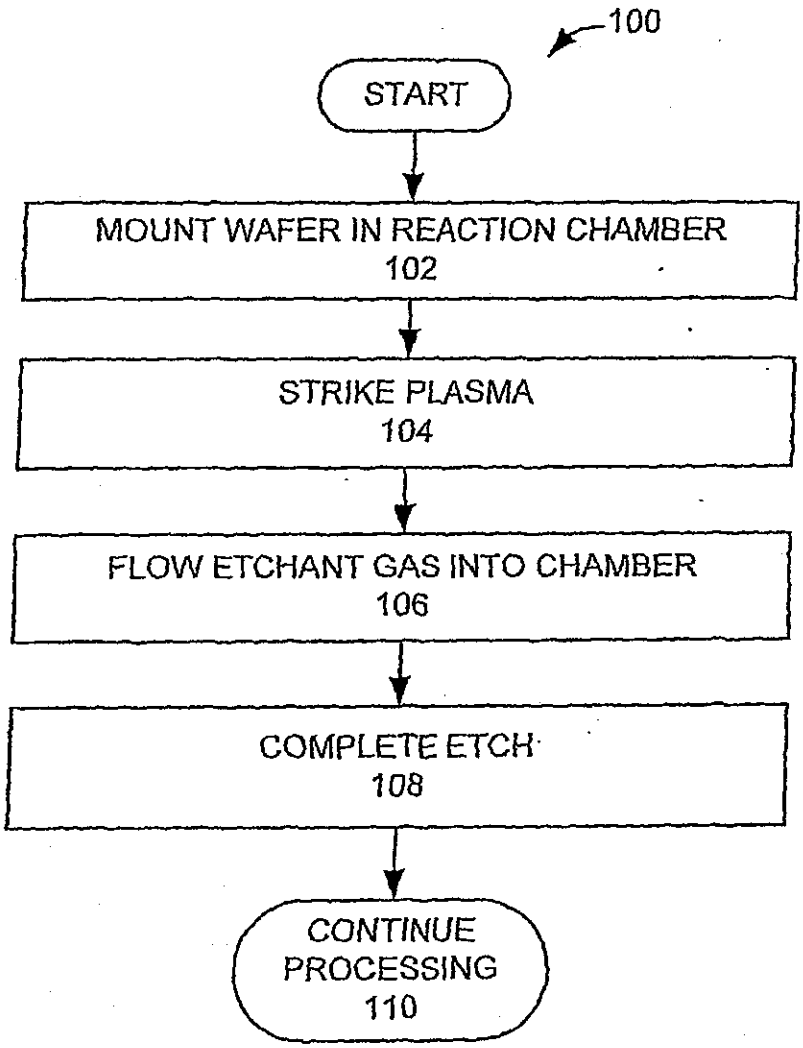

100
START
MOUNT WAFER IN REACTION CHAMBER
102
STRIKE PLASMA
104
FLOW ETCHANT GAS INTO CHAMBER
106
COMPLETE ETCH
108
CONTINUE
PROCESSING
110

FIG. 2

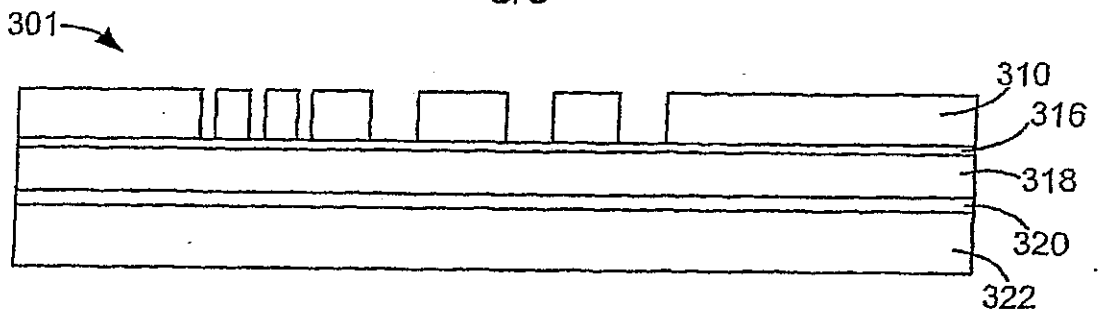


FIG. 3A

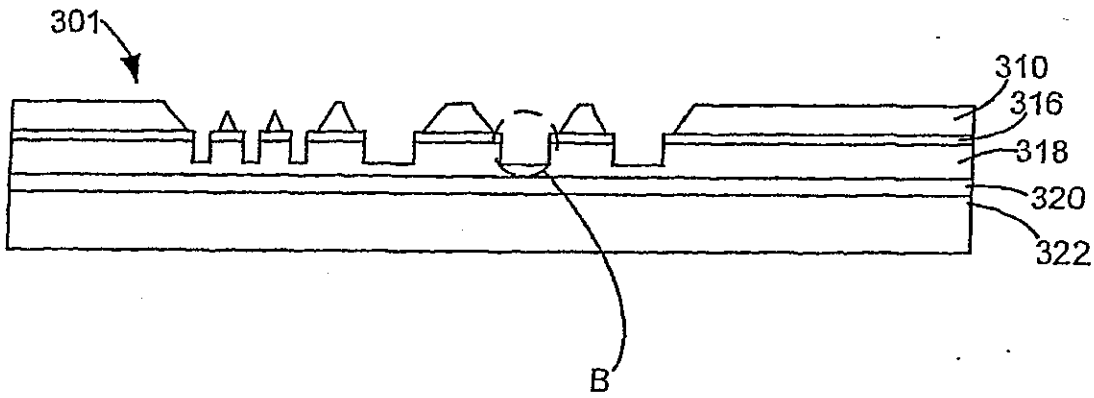


FIG. 3B

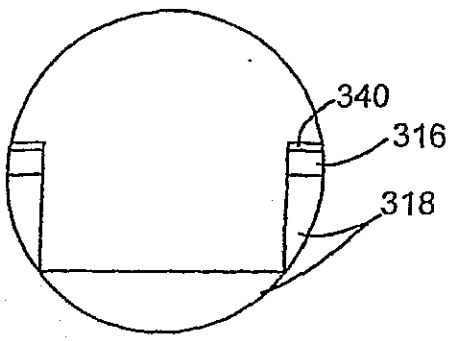


FIG. 3C

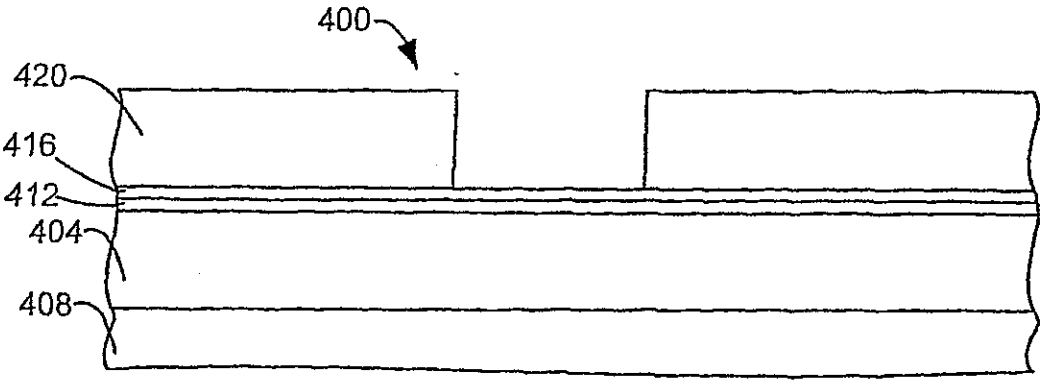


FIG. 4A

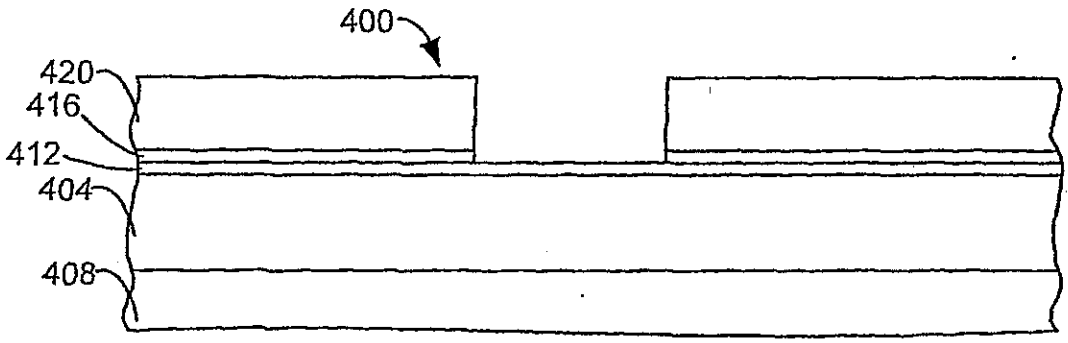


FIG. 4B

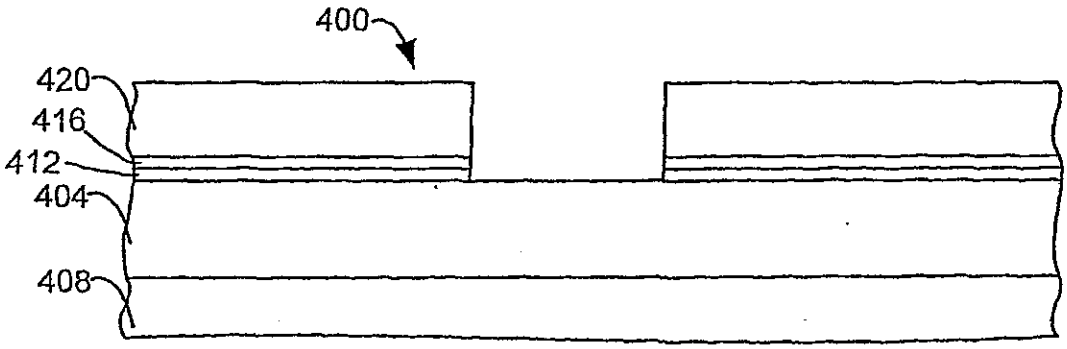


FIG. 4C

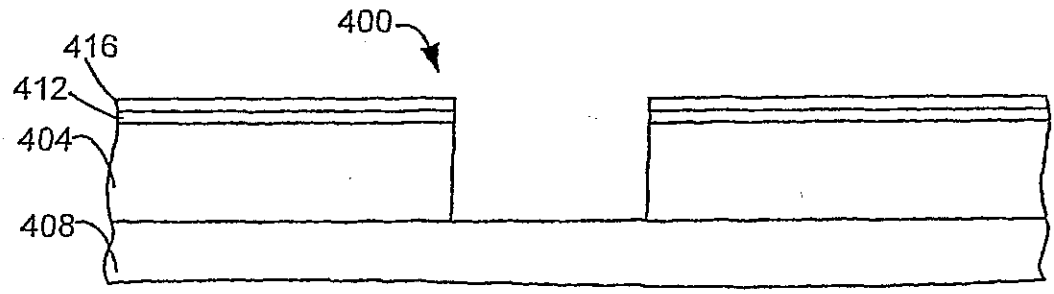


FIG. 4D

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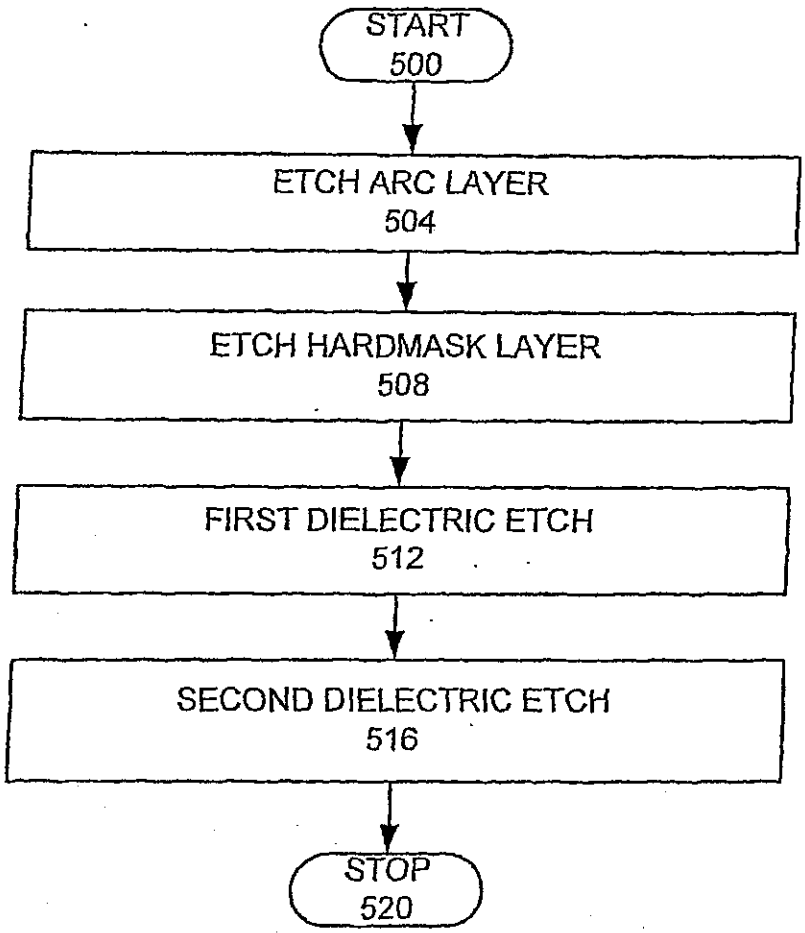


FIG. 5